

SEMICONDUCTOR DEVICE WITH MAGNETICALLY PERMEABLE
HEAT SINK

Abstract of the Disclosure

5 A semiconductor device is attached to a heat sink by glue that is both
thermally conductive and magnetically permeable. The glue fills different
features in the surface of the semiconductor device so that there is good
coupling between the semiconductor device and the heat sink. The glue is filled
with magnetic particles so that the glue is magnetically permeable. The
10 semiconductor device is formed with the heat sink at the wafer level and then
singulated after attachment of the heat sink with the glue.